SCCS029A - MAY 1994 - REVISED OCTOBER 2001

- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT540T
 - 48-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT540T
 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

description

The 'FCT540T inverting buffers/line drivers can be employed as memory address drivers, clock drivers, and bus-oriented transmitters/receivers. These devices provide speed and drive capabilities equivalent to their fastest bipolar-logic counterparts, while reducing power dissipation. The input and output voltage levels allow direct interface with TTL, NMOS, and CMOS devices without external components.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

T _A	PACI	KAGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	4.1	CY74FCT540CTQCT	FCT540C
–55°C to 125°C	CDIP – D	Tube	4.7	CY54FCT540CTDMB	
-55 C 10 125 C	LCC – L	Tube	4.7	CY54FCT540CTLMB	

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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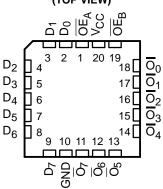
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2001, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CY54FCT CY74FCT		QF	
OE _A D ₀ D ₁ D ₂ D ₃ D ₄ D ₅ D ₆ GND	1 2 3 4 5 6 7 8 9 10	20 19 18 17 16 15 14 13 12 11	$\frac{V_{CC}}{\overline{OE}_{B}}$ \overline{OO}_{1} \overline{OO}_{2} \overline{OO}_{2} \overline{OO}_{3} \overline{OO}_{4} \overline{OO}_{5} \overline{OO}_{7}

CY54FCT540T . . . L PACKAGE (TOP VIEW)



CY54FCT540T, CY74FCT540T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS SCCS029A – MAY 1994 – REVISED OCTOBER 2001

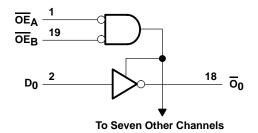
FUNCTION TABLE

	INPUTS	OUTPUT	
OEA	OEB	D	ō
L	L	L	н
L	L	Н	L
Н	Н	Х	Z

H = High logic level, L = Low logic level,

X = Don't care, Z = High-impedance state

logic diagram (positive logic)



absolute maximum rating over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		CY	54FCT54	0Т	CY	74FCT54	OT	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-32	mA
IOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEAT CONDITI	210	CY	54FCT54	ют	CY	74FCT54	OT	
PARAMETER		TEST CONDITION	DNS	MIN	түр†	MAX	MIN	TYP [†]	MAX	UNIT
Maria	V _{CC} = 4.5, V	I _{IN} = -18 mA			-0.7	-1.2				V
VIK	V _{CC} = 4.75 V,	I _{IN} = -18 mA						-0.7	-1.2	v
	V _{CC} =4.5 V,	I _{OH} = -12 mA		2.4	3.3					
VOH	V _{CC} = 4.75 V	I _{OH} = -32 mA					2			V
	VCC = 4.75 V	I _{OH} = -15 mA					2.4	3.3		
Ve	V _{CC} = 4.5 V,	l _{OL} = 48 mA			0.3	0.55				V
VOL	V _{CC} = 4.75 V,	I _{OL} = 64 mA						0.3	0.55	v
V _{hys}	All inputs				0.2			0.2		V
	V _{CC} = 5.5 V,	$V_{IN} = V_{CC}$				5				A
łı	V _{CC} = 5.25 V,	$V_{IN} = V_{CC}$							5	μA
l	V _{CC} = 5.5 V,	V _{IN} = 2.7 V				±1				
ΙΗ	V _{CC} = 5.25 V,	V _{IN} = 2.7 V							±1	μA
I	V _{CC} = 5.5 V,	V _{IN} = 0.5 V				±1				۵
ΗL	V _{CC} = 5.25 V,	V _{IN} = 0.5 V							±1	μA
1	V _{CC} = 5.5 V,	V _{OUT} = 2.7 V				10				A
IOZH	V _{CC} = 5.25 V,	V _{OUT} = 2.7 V							10	μA
1	V _{CC} = 5.5 V,	V _{OUT} = 0.5 V				-10				A
IOZL	V _{CC} = 5.25 V,	V _{OUT} = 0.5 V							-10	μA
1	V _{CC} = 5.5 V,	V _{OUT} = 0 V		-60	-120	-225				
IOS‡	V _{CC} = 5.25 V,	V _{OUT} = 0 V					-60	-120	-225	mA
l _{off}	$V_{CC} = 0 V,$	V _{OUT} = 4.5 V				±1			±1	μA
laa	V _{CC} = 5.5 V,	$V_{IN} \leq 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 V$		0.1	0.2				~ ^
lcc	V _{CC} = 5.25 V,	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 V$					0.1	0.2	mA
	V _{CC} = 5.5 V, V _{IN}	= 3.4 V§, f ₁ = 0, O	utputs open		0.5	2				
∆ICC	V _{CC} = 5.25 V, V _I	N = 3.4 V§, f ₁ = 0, 0	Dutputs open					0.5	2	mA
	One bit switching	ID or $\overline{OE}_A = GND$ a	·		0.06	0.12				mA/
ICCD	V _{CC} = 5.25 V, 50 ^o One bit switching	% duty cycle, Output at $f_1 = 10 \text{ MHz}$, ID or $\overline{OE}_A = \text{GND} \text{ at}$ $N \ge V_{CC} - 0.2 \text{ V}$						0.06	0.12	MHz

[†] Typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

* Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

This parameter is derived for use in total power-supply calculations.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

		TEST CONDITION	.	CY	54FCT54	ЮT	CY	74FCT54	0T	UNIT
PARAMETER		TEST CONDITIONS				MAX	MIN	TYP†	MAX	UNIT
	V _{CC} = 5.5 V, Outputs open,	One bit switching at f ₁ = 10 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$		0.7	1.4				
	$\overline{OE}_A = \overline{OE}_B =$	at 50% duty cycle	V_{IN} = 3.4 V or GND		1	2.4				
	GND or $OE_A = GND$ and	Eight bits switching at f ₁ = 2.5 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ \text{or} \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$		1.3	2.6				
'C#	$\overline{OE}_{B} = V_{CC}$	at 50% duty cycle	V_{IN} = 3.4 V or GND		3.3	10.6				mA
'C"	V _{CC} = 5.25 V, Outputs open,	One bit switching at f ₁ = 10 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ \text{or} \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$					0.7	1.4	ША
	$\overline{OE}_A = \overline{OE}_B =$	at 50% duty cycle	V_{IN} = 3.4 V or GND					1	2.4	
	GND or $OE_A = GND$ and	Eight bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1.3	2.6II	
	$\overline{OE}_{B} = V_{CC}$	at 50% duty cycle	V_{IN} = 3.4 V or GND					3.3	10.6	
Ci								5	10	pF
Co								9	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [#] $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

IC = Total supply current

ICC = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

 D_H = Duty cycle for TTL inputs high NT = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero fo

f1 = Input signal frequency

= Number of inputs changing at f1 N₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



CY54FCT540T, CY74FCT540T **8-BIT BUFFERS/LINE DRIVERS** WITH 3-STATE OUTPUTS SCCS029A – MAY 1994 – REVISED OCTOBER 2001

switching characteristics over operating free-air temperature range (see Figure 1)

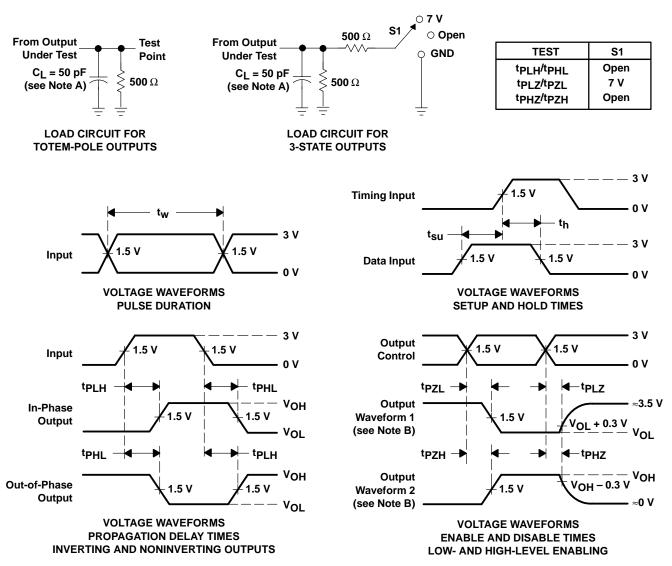
PARAMETER	FROM	то	CY54FCT	540CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	UNIT
^t PLH	D	ō	1.5	4.7	200
^t PHL	ם	0	1.5	4.7	ns
^t PZH	ŌĒ	ō	1.5	6.5	20
tPZL	0E	0	1.5	6.5	ns
^t PHZ	ŌĒ	ō	1.5	5.7	200
^t PLZ	UE UE	0	1.5	5.7	ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	UNIT
^t PLH	D	ō	1.5	4.1	
^t PHL	d	0	1.5	4.1	ns
^t PZH	ŌĒ	ō	1.5	5.8	200
^t PZL	OE	0	1.5	5.8	ns
^t PHZ	OE	-	1.5	5.2	
^t PLZ	OE	0	1.5	5.2	ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





9-Mar-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9222006MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9222006MR A	Samples
5962-9223701M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223701M2A CY54FCT 541TLMB	Samples
5962-9223701MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223701MR A CY54FCT541TDMB	Samples
5962-9223705MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223705MR A	Samples
CY54FCT541TDMB	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223701MR A CY54FCT541TDMB	Samples
CY54FCT541TLMB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223701M2A CY54FCT 541TLMB	Samples
CY74FCT540CTQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT540C	Samples
CY74FCT540CTQCTE4	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT540C	Samples
CY74FCT541ATPC	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	CY74FCT541ATPC	Samples
CY74FCT541ATQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT541A	Samples
CY74FCT541ATSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541A	Samples
CY74FCT541ATSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541A	Samples
CY74FCT541CTQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT541C	Samples
CY74FCT541CTSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541C	Samples
CY74FCT541CTSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541C	Samples



9-Mar-2021

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT541CTSOCTE4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541C	Samples
CY74FCT541TQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT541	Samples
CY74FCT541TSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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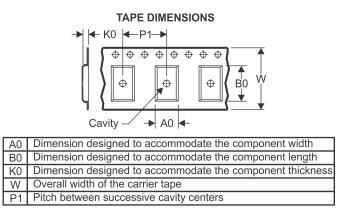
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT540CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT541ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT541ATSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT541CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT541CTSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT541TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT540CTQCT	SSOP	DBQ	20	20 2500 853.0		449.0	35.0
CY74FCT541ATQCT	SSOP	DBQ	20	2500	853.0	449.0	35.0
CY74FCT541ATSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT541CTQCT	SSOP	DBQ	20	2500	853.0	449.0	35.0
CY74FCT541CTSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT541TQCT	SSOP	DBQ	20	2500	853.0	449.0	35.0



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TUBE



*All	dimensions	are	nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9223701M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
CY54FCT541TLMB	FK	LCCC	20	1	506.98	12.06	2030	NA
CY74FCT541ATPC	N	PDIP	20	20	506	13.97	11230	4.32
CY74FCT541ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT541CTSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT541TSOC	DW	SOIC	20	25	507	12.83	5080	6.6

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